TOSHIBA Rectifier Silicon Diffused Type

# CMG07

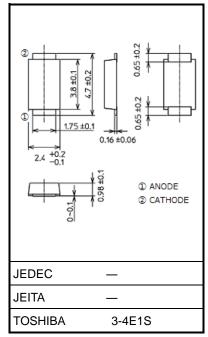
#### ○ General-Purpose Rectifiers

- Repetitive peak reverse voltage : V<sub>RRM</sub> = 400 V
- Average forward current : IF(AV) = 1 A
- Peak forward voltage :  $V_{FM} = 1.1 V (max) @I_F = 1 A$
- Suitable for high-density board assembly due to the use of a small Toshiba Nickname: M-FLAT<sup>TM</sup>

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	Vrrm	400	V
Average forward current	IF (AV)	1 (Note1)	А
Non-repetitive peak forward surge current	IFSM	30 (50 Hz)	А
Junction temperature	Тј	150	°C
Storage temperature	T <sub>stg</sub>	-40 to 150	°C

Note1: Ta=78°C Device mounted on a ceramic board Board size :  $50 \text{ mm} \times 50 \text{ mm}$ Soldering land size :  $2 \text{ mm} \times 2 \text{ mm}$ Board thickness : 0.64 mmRectangular waveform :  $\alpha = 180^{\circ}$ 



Weight: 0.023 g (typ.)

Note 2: Using continuously under heavy loads (e.g. the application

of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Electrical Characteristics (Ta = 25°C)**

Characteristics	Symbol	Test Condition		Тур.	Max	Unit
	VFM (1)	I <sub>FM</sub> = 0.1 A (pulse test)		0.80	—	
Peak forward voltage	VFM (2)	IFM = 0.7 A (pulse test)	-	0.91	_	V
	VFM (3)	I <sub>FM</sub> = 1 A (pulse test)		0.94	1.1	
Peak repetitive reverse current	IRRM	V <sub>RRM</sub> = 400 V (pulse test)	Ι	—	10	μΑ
Thermal resistance (junction to ambient)		$\begin{array}{llllllllllllllllllllllllllllllllllll$	_	_	60	
	Rth (j-a)	Device mounted on a glass-epoxy board         board size       50 mm × 50 mm         soldering land size       6 mm × 6 mm         board thickness       1.6 mm	_	_	125	°C/W
		$\begin{array}{ccc} \text{Device mounted on a glass-epoxy board} \\ \text{board size} & 50 \text{ mm} \times 50 \text{ mm} \\ \text{soldering land size} & 2.1 \text{ mm} \times 1.4 \text{ mm} \\ \text{board thickness} & 1.6 \text{ mm} \end{array}$	_	_	200	
Thermal resistance (junction to lead)	R <sub>th (j-ℓ)</sub>	_		_	16	°C/W

Start of commercial production 2008-10

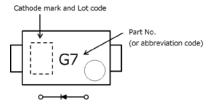
#### 2018-07-06

Unit: mm

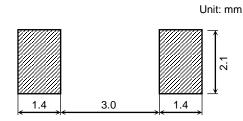
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#### Marking

Abbreviation Code	Part No.
G7	CMG07



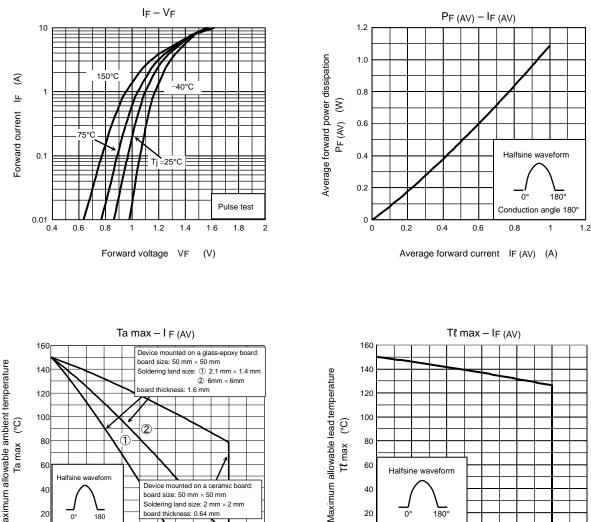
#### Land pattern dimensions for reference only

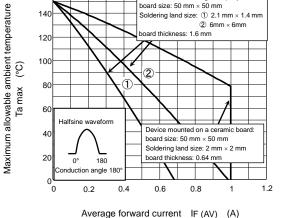


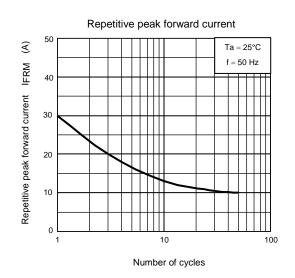
#### **Handling Precaution**

- The absolute maximum ratings are rated values that must not be exceeded during operation, even for aninstant. The following are the recommended general derating methods for designing a circuit board usingthis device.
  - VRRM : We recommend that the worst case voltage, including surge voltage, be no greater than 80% of the absolute maximum rating of VRRM for a DC circuit and be no greater than 50% of that of VRRM for an AC circuit. VRRM has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.
  - IF (AV) :We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF (AV) and Tj be below 120°C. When using this device, take the margin into consideration by using an allowable Ta max-IF (AV) curve.
  - IFSM :This rating specifies peak non-repetitive forward surge current. This only applies to an abnormal operation, which seldom occurs during the lifespan of a device.
  - Tj :Derate device parameters in proportion to this rating in order to ensure high reliability. We recommend that the junction temperature (Tj) of a device be kept below 120°C.
- 2) Thermal resistance (junction-to-ambient) varies with the mounting conditions of a device on a circuit board. An appropriate thermal resistance value should be used, considering the circuit board design and land pattern dimensions (provided for reference only).
- 3) For other design considerations, see the Toshiba website.

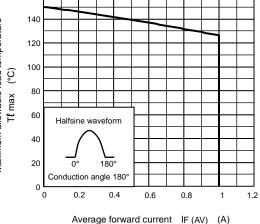
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ľth (j-a) – t 1000 Device mounted on a glass-epoxy boar board size: 50 mm × 50 mm Soldering land size: 2.1 mm × 1.4 mm board thickness: 1.6 mm 1.6 100 rth (j-a) (°C/W) Device mounted on a glass-epoxy board size: 50 mm × 50 mm Soldering land size: 6 mm × 6 mm board thickness: 1.6 mm 10 size: 50 mm × 50 mm ing land: size 2 mm × 2 mm thickness: 0.64 mm 0.001 0.01 0.1 10 100 1000 1 Time t (s)



Transient thermal resistance

## TOSHIBA

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